



The **leading equipment manufacturer** for sub-micron die bonding and advanced SMD rework.

We provide solutions for each stage of your journey - from R&D to industrial automated production.



...simply accurate

Manual to Fully Automated Bonding Equipment for Photonics Packaging

Prototyping

Research & Development

High Yield Production

FINEPLACER® lambda 2



- $\pm 0.5\mu\text{m}$ placement accuracy
- Manual or motorized arm
- Dice from waffle- & gel packs

FINEPLACER® sigma



- $\pm 0.5\mu\text{m}$ placement accuracy
- Semi-automatic system
- With vision system
- Dice from wafers, waffle- & gel packs

FINEPLACER® femto 2



- $\pm 0.3\mu\text{m}$ placement accuracy
- Automatic system
- Dice from wafers, waffle- & gel packs
- Multi chip capability

FineXT™ 6003



- $\pm 3.0\mu\text{m}$ placement accuracy
- Modes for speed & accuracy
- Fully automatic system
- Multi chip capability
- Very large work area

Finetech's Offers for Photonics Packaging

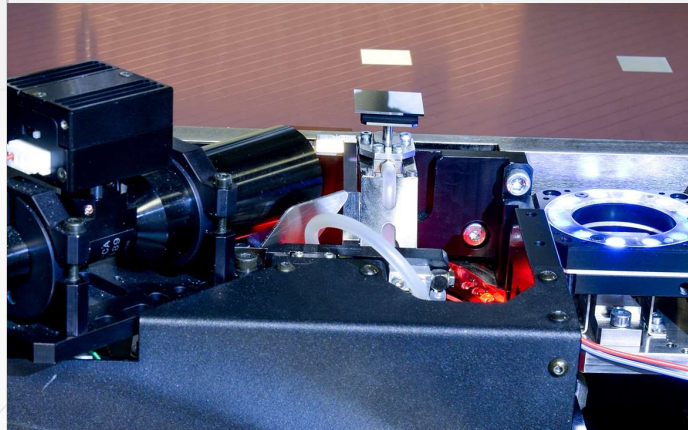
Technologies & Methods

- Adhesive bonding (incl. UV curing)
- Soldering / eutectic soldering
- Thermocompression bonding
- Laser-assisted bonding (LAB)
- Active alignment (by external position control)



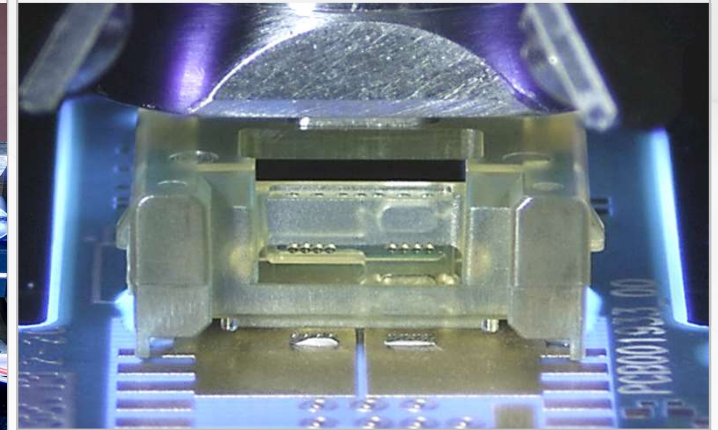
Processes

- Precision die bonding (face up)
- Flip chip bonding (face down)
- Multi chip packaging (MCM, MCP)
- Chip on Substrate/Submount (CoS)
- Chip on Board (CoB)



Components

- VCSEL & DFB Lasers and Bars
- Edge Emitting Lasers Diode and Bars
- HCSELs & LISELs
- Photodiodes (PD)
- Laser Diode Driver (LDD) & Transimpedance Amplifier (TIA)
- Submounts
- **Lenses** (using [Finetech's unique passive alignment method](#))
- μ LED / miniLED



What Finetech can do for you and what you can do for Finetech?

What Finetech can do for you

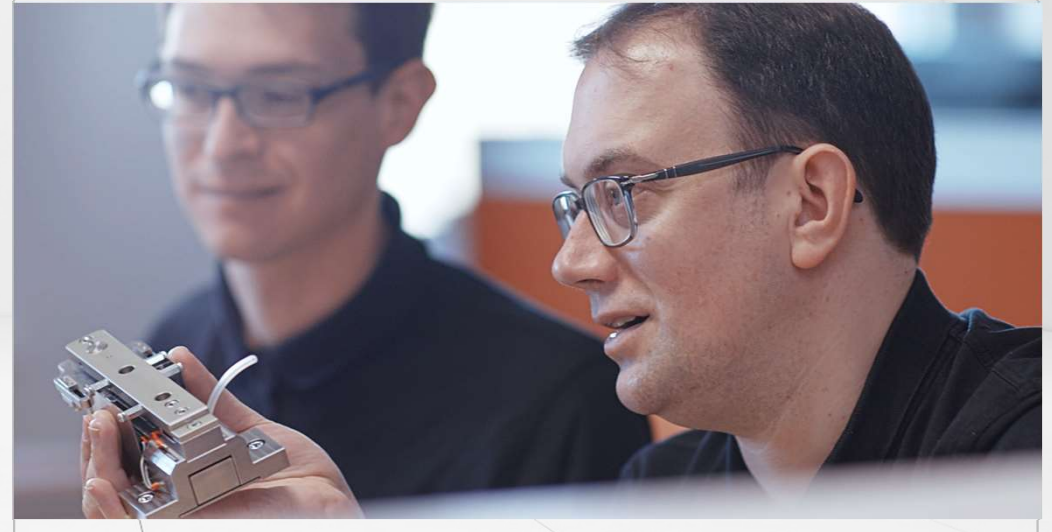
- Building samples *)
- Process co-development *)
- Small lot production in our clean room on our demo equipment *)

*) material to be provided by customer



What you can do for Finetech

- Get us involved at an early stage for new product developments
- Contact us, if you look for a tailored equipment solution
- Get in touch with us for new process developments



Call us

+49 30 93 66 81 300



Contact us

finetech.de/contact/

Finetech's Unique Passive Lens Alignment Method

Warning: Safety equipment has been deactivated (key switch "Service")

finetech 17:33 20/04/2020

Mode: Operation
Group: lens
Process: **lens (Pick up)**
Recognize 'Lens' at X:3 Y:1
Pattern recognition Snap camera images

Start Stop

X	534.596	Y	60.379	Z	2.850
P	0.000	W	90.000	W _F	0.000
M _X	0.000				

Camera / Light Actions

Process

Camera FPX

Camera FPX

Video

Change

Aligning

P2

P1

Sensors

Full screen